

NOTE:
100053FB010□□00ZL

1. Selective plating
 S1-05u"Min.Gold in contact area/
 100u"Min.Tin in solder area.
 S2-Gold flash in contact area/
 100u"Min.Tin in solder area.
 S3-10u"Min.Gold in contact area/
 100u"Min.Tin in solder area.
 S4-15u"Min.Gold in contact area/
 100u"Min.Tin in solder area.
 S5-30u"Min.Gold in contact area/
 100u"Min.Tin in solder area.
 S6-50u"Min.Gold in contact area/
 100u"Min.Tin in solder area.

Notes:

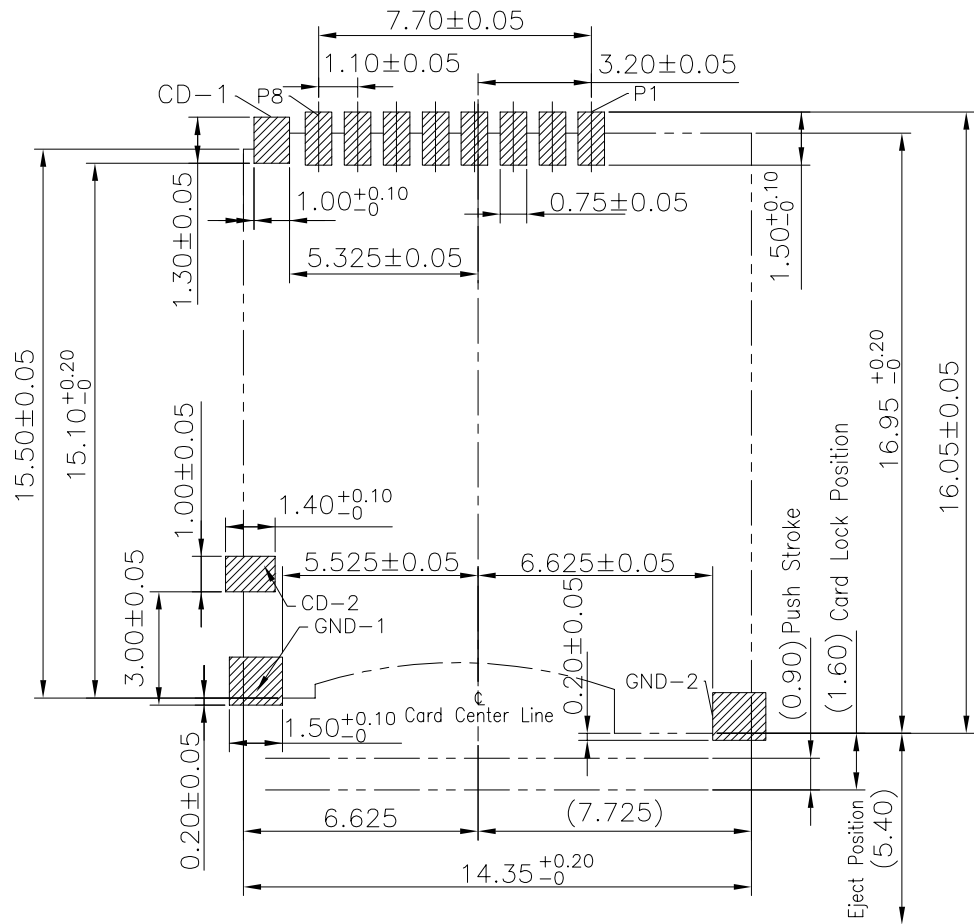
- Material:
 1-1 Housing:LCP,Black,UL94V-0.
 1-2 Terminal:Phosphor Bronze.
 1-3 Shell:Stainless Steel.
- Plating in Contact:
 2-1 Under-Plate Nickel All Over.
 2-2 Plate Gold In Contact Area.
 2-3 Plate Tin Lead In Tail Zone.
- Coplanarity:0.12 Max.

2	TERMINAL	CS210-EH	—	GOLD/TIN PLATED
1	PLASTIC	LCP	BLACK	UL94V-0
NO.	DESCRIPTION	MATERIAL	COLOR	REMARK

SUYIN
CONNECTOR

CUSTOMER COPY	TITLE: TFR P-P TOP CONNECTOR
PART NO.	100053FB010SX00ZL
PART NO.(OLD)	—
DRAWING NO.	C ING 100053FB010SX00ZL
SCALE	5:1
UNIT	mm
A4	⊕

ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED
			NEW			Angle ±2° 30 ~ ±0.50 10 ~ 30 ±0.30 ~ 10 ±0.15
						DRAW DESIGN CHECK APPRO.



Recommended PCB Layout

: Pad Area
 - - - - : Keep Out Area

Memory Card Pin Assignment

Pad No.	Pin Assignment
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	Vss2
P7	DAT0
P8	DAT1
CD-1	Card Detect Switch
CD-2	Card Detect Com.
GND-1	Chassis GND
GND-2	Chassis GND

Switch States

Switch State	CD-1/CD-2
Without Card	Open
Card Inserted	Close

ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	ANGLE	±2°	DRAW
			NEW				30 ~	±0.50	
							10 ~ 30	±0.30	
							~ 10	±0.15	

NO.	DESCRIPTION	MATERIAL	COLOR	REMARK
2				
1				

SUYIN
CONNECTOR

CUSTOMER COPY	TITLE: TFR P-P TOP CONNECTOR LAYOUT DRAWING
PART NO.	100053FB010SX00ZL
PART NO.(OLD)	
DRAWING NO.	100053FB010SX00ZL
SCALE	5:1
UNIT	mm
A4	